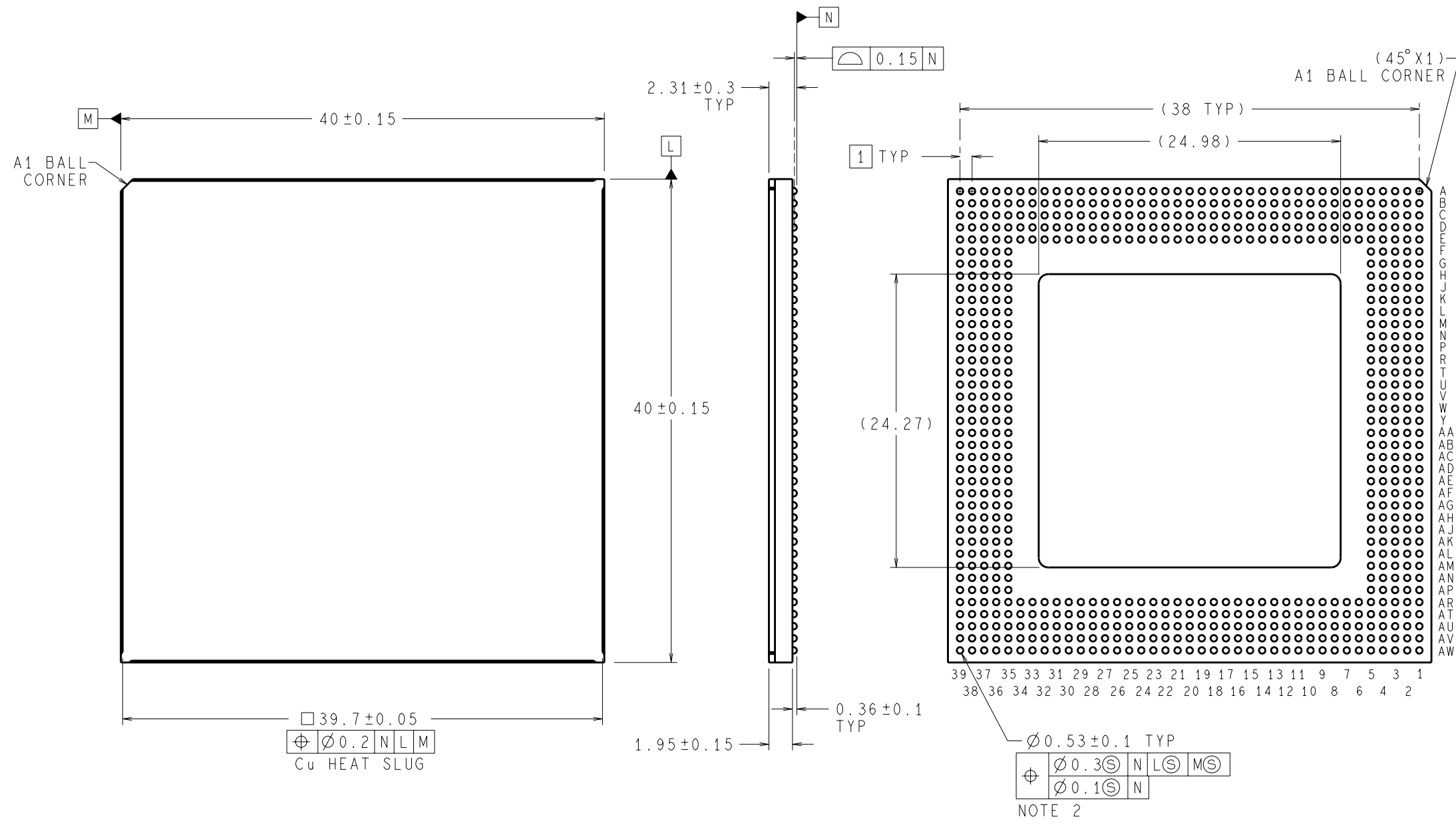


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12212	05/07/1999	MS/MJL
B	DIM'S 1.95 WAS 1.88; 2.31 WAS 2.24; REVISE TITLE	12255	07/06/1999	MS/



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
2. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
3. REFERENCE JEDEC REGISTRATION MO-151, VARIATION -1.00, DATED JUNE 1997.

APPROVALS	DATE	National Semiconductor			
DRAWN MARTA SUCHY	05/07/1999	2900 Semiconductor dr., Santa Clara, CA 95052-8090			
DFTG. CHK.		EBGA, 40 X 40 X 2.31mm, 680 BALL, 1.0mm PITCH			
ENGR. CHK.					
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-UCK680A	B
DO NOT SCALE DRAWING				SHEET 1 of 1	